

EXPRESS MAIL NO.: EL 477 033 757 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Fukutomi et al.

Group Art Unit: to be assigned

Serial No.: to be assigned
(Continuation of 10/008,616)

Examiner: to be assigned

Attorney Docket No.: 7426-082

Filed: concurrently filed

New York, NY
January 8, 2002

For: FABRICATION PROCESS OF
SEMICONDUCTOR PACKAGE AND
SEMICONDUCTOR PACKAGE

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Applicants respectfully request entry of the following amendment and
remarks in to the file of the above identified application.

IN THE CLAIMS:

Please cancel claims 1-13.

Please add the following new claims:

14. (New)

A method of producing a substrate for mounting semiconductor
devices thereon, said substrate having an insulating supporting member and plural
sets of wiring, comprising the steps of:

200408-010800

SUB B17
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